

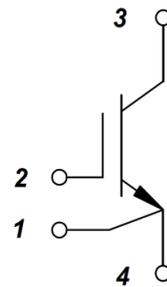
PRODUCT FEATURES

- IGBT CHIP(Trench+Field Stop technology)
- Low switching losses
- Low saturation voltage and positive temperature coefficient
- Fast switching and short tail current
- Popular SOT-227 Package
- $T_{Jmax}=175^{\circ}C$



APPLICATIONS

- AC motor control
- Motion/servo control
- Inverter and power supplies



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ABSOLUTE MAXIMUM RATINGS($T_C=25^{\circ}C$ unless otherwise specified)

Symbol	Parameter/Test Conditions		Values	Unit
V_{CES}	Collector Emitter Voltage	$T_J=25^{\circ}C$	1200	V
V_{GES}	Gate Emitter Voltage		± 20	
I_C	DC Collector Current	$T_C=25^{\circ}C, T_{Jmax}=175^{\circ}C$	147	A
		$T_C=95^{\circ}C, T_{Jmax}=175^{\circ}C$	100	
I_{CM}	Repetitive Peak Collector Current	$t_p=1ms$	200	
P_{tot}	Power Dissipation Per IGBT	$T_C=25^{\circ}C, T_{Jmax}=175^{\circ}C$	515	W

MODULE CHARACTERISTICS ($T_C=25^{\circ}C$ unless otherwise specified)

Symbol	Parameter/Test Conditions		Values	Unit
T_{Jmax}	Max. Junction Temperature		175	$^{\circ}C$
T_{Jop}	Operating Temperature		-40~150	
T_{stg}	Storage Temperature		-40~125	
V_{isol}	Isolation Breakdown Voltage	AC, 50Hz(R.M.S), $t=1minute$	3000	V
Torque	to heatsink	Recommended (M4)	0.7~1.1	Nm
	to terminal	Recommended (M4)	0.7~1.1	Nm
Weight			26.5	g

MacMic Science & Technology Co., Ltd.

Add: #18, Hua Shan Zhong Lu, New District, Changzhou City, Jiangsu Province, P. R. of China

MMG100J120UZ6TC

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ELECTRICAL CHARACTERISTICS ($T_C=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter/Test Conditions		Min.	Typ.	Max.	Unit
$V_{GE(th)}$	Gate Emitter Threshold Voltage	$V_{CE}=V_{GE}, I_C=4\text{mA}$	5.0	6.0	6.5	V
$V_{CE(sat)}$	Collector Emitter Saturation Voltage	$I_C=100\text{A}, V_{GE}=15\text{V}, T_J=25^\circ\text{C}$		1.85	2.25	
		$I_C=100\text{A}, V_{GE}=15\text{V}, T_J=125^\circ\text{C}$		2.10		
		$I_C=100\text{A}, V_{GE}=15\text{V}, T_J=150^\circ\text{C}$		2.15		
I_{CES}	Collector Leakage Current	$V_{CE}=1200\text{V}, V_{GE}=0\text{V}, T_J=25^\circ\text{C}$			1	mA
		$V_{CE}=1200\text{V}, V_{GE}=0\text{V}, T_J=150^\circ\text{C}$			10	mA
I_{GES}	Gate Leakage Current	$V_{CE}=0\text{V}, V_{GE}=\pm 20\text{V}, T_J=25^\circ\text{C}$	-400		400	nA
R_{gint}	Integrated Gate Resistor			7		Ω
Q_g	Gate Charge	$V_{CE}=600\text{V}, I_C=100\text{A}, V_{GE}=15\text{V}$		0.53		μC
C_{ies}	Input Capacitance	$V_{CE}=25\text{V}, V_{GE}=0\text{V}, f=1\text{MHz}$		7.1		nF
C_{res}	Reverse Transfer Capacitance				300	
$t_{d(on)}$	Turn on Delay Time	$V_{CC}=600\text{V}, I_C=100\text{A}$ $R_G=5.1\Omega,$ $V_{GE}=\pm 15\text{V},$ Inductive Load	$T_J=25^\circ\text{C}$	170		ns
			$T_J=150^\circ\text{C}$	190		ns
t_r	Rise Time		$T_J=25^\circ\text{C}$	50		ns
			$T_J=150^\circ\text{C}$	56		ns
$t_{d(off)}$	Turn off Delay Time	$V_{CC}=600\text{V}, I_C=100\text{A}$ $R_G=5.1\Omega,$ $V_{GE}=\pm 15\text{V},$ Inductive Load	$T_J=25^\circ\text{C}$	350		ns
			$T_J=150^\circ\text{C}$	410		ns
t_f	Fall Time		$T_J=25^\circ\text{C}$	100		ns
			$T_J=150^\circ\text{C}$	190		ns
E_{on}	Turn on Energy	$V_{CC}=600\text{V}, I_C=100\text{A}$ $R_G=5.1\Omega,$ $V_{GE}=\pm 15\text{V},$ Inductive Load	$T_J=25^\circ\text{C}$	11.5		mJ
			$T_J=150^\circ\text{C}$	16.2		mJ
E_{off}	Turn off Energy		$T_J=25^\circ\text{C}$	5.6		mJ
			$T_J=150^\circ\text{C}$	9.1		mJ
I_{SC}	Short Circuit Current	$tp_{sc} \leq 10\mu\text{s}, V_{GE}=15\text{V}$ $T_J=125^\circ\text{C}, V_{CC}=800\text{V}$		420		A
R_{thJC}	Junction to Case Thermal Resistance (Per IGBT)				0.29	K/W

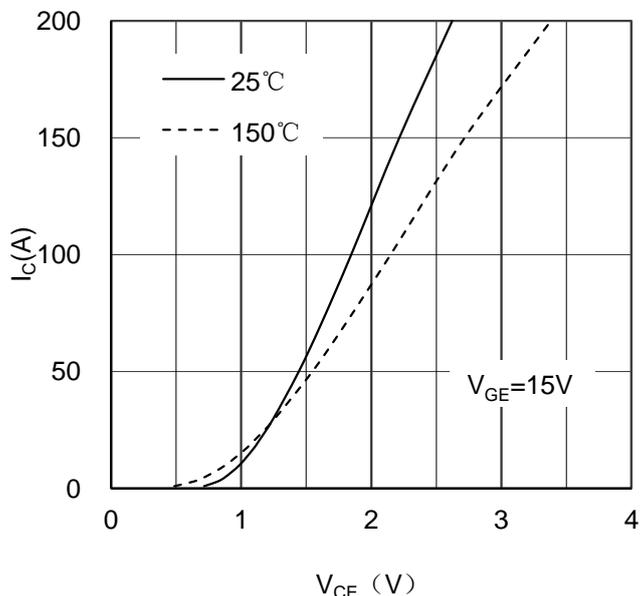


Figure 1. Typical Output Characteristics IGBT

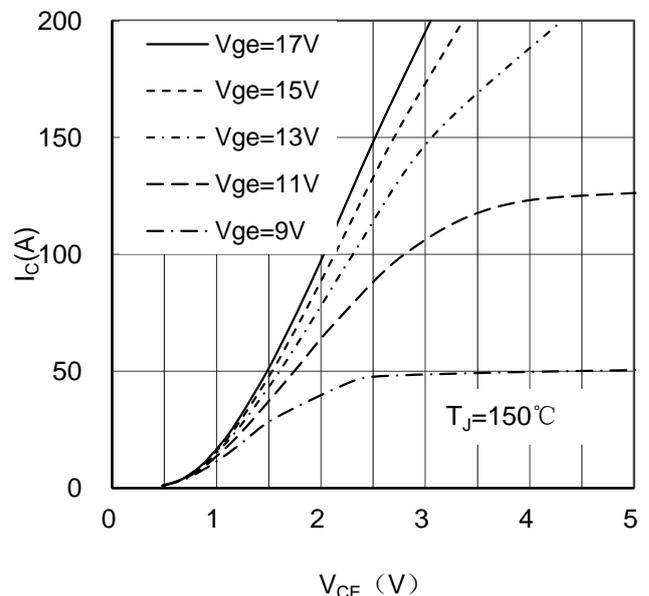


Figure 2. Typical Output Characteristics IGBT

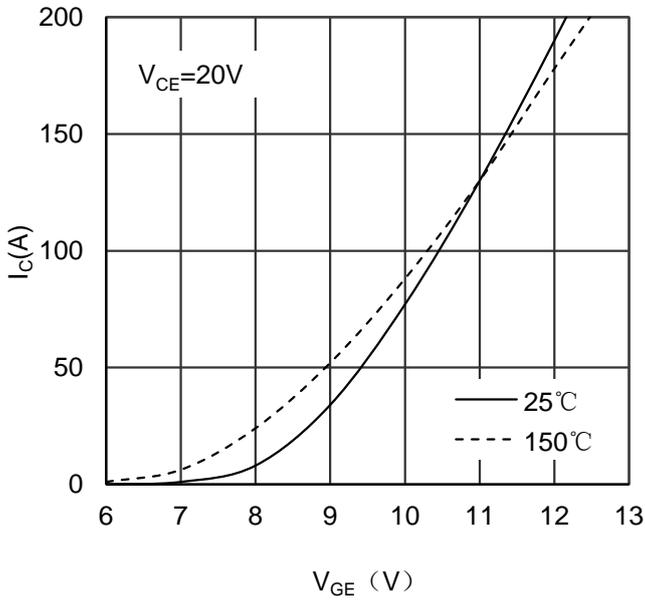


Figure 3. Typical Transfer characteristics IGBT

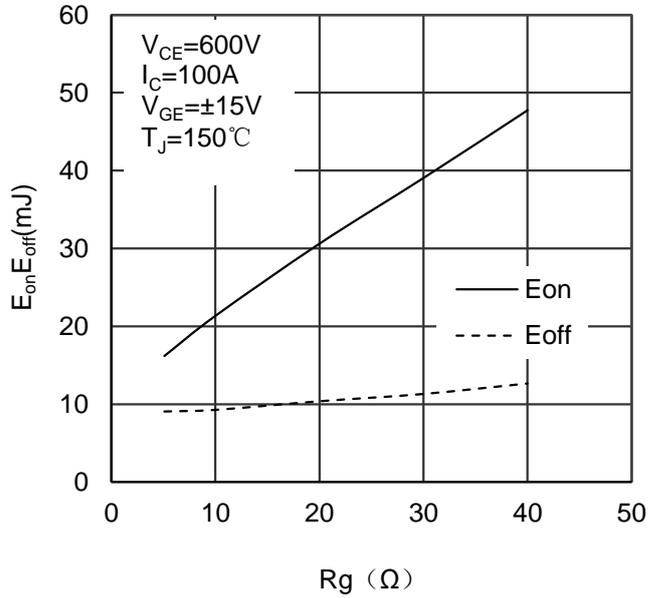


Figure 4. Switching Energy vs Gate Resistor IGBT

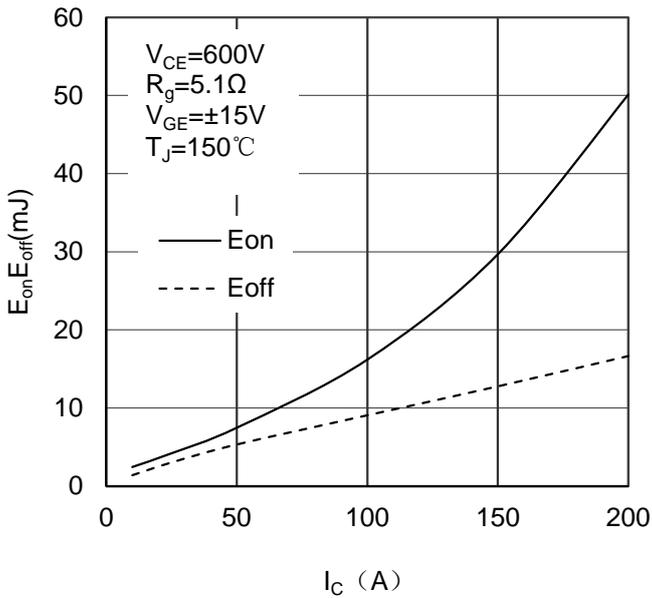


Figure 5. Switching Energy vs Collector Current IGBT

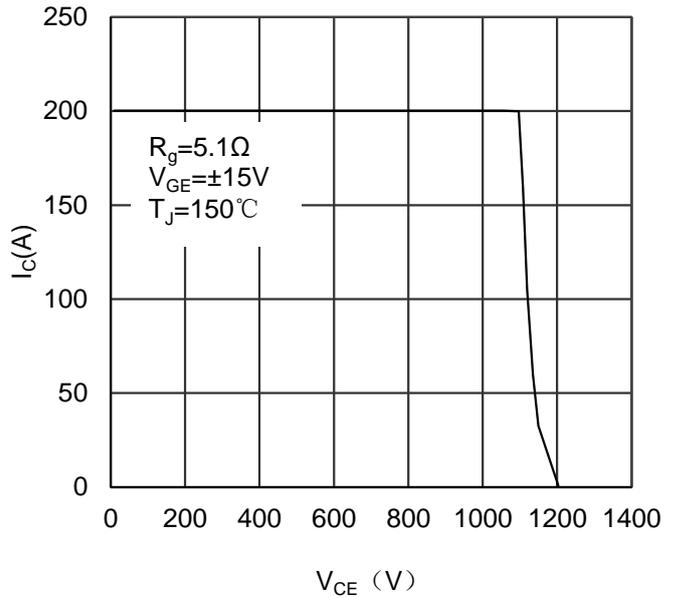


Figure 6. Reverse Biased Safe Operating Area IGBT

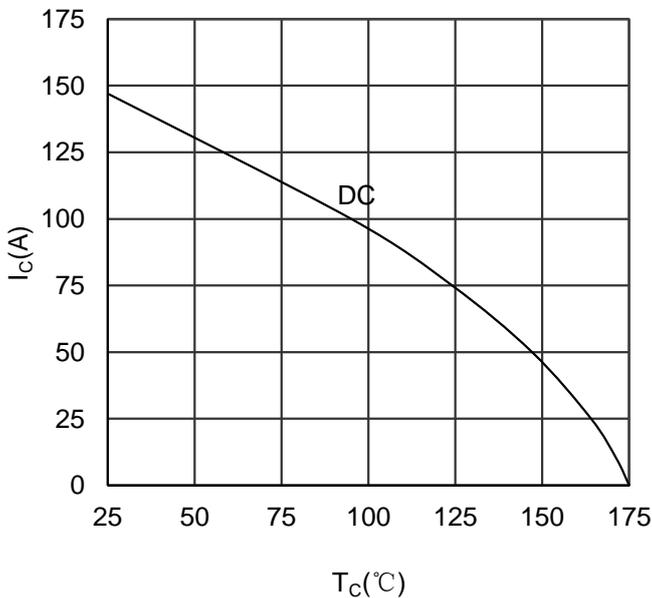


Figure 7. Collector Current vs Case temperature IGBT

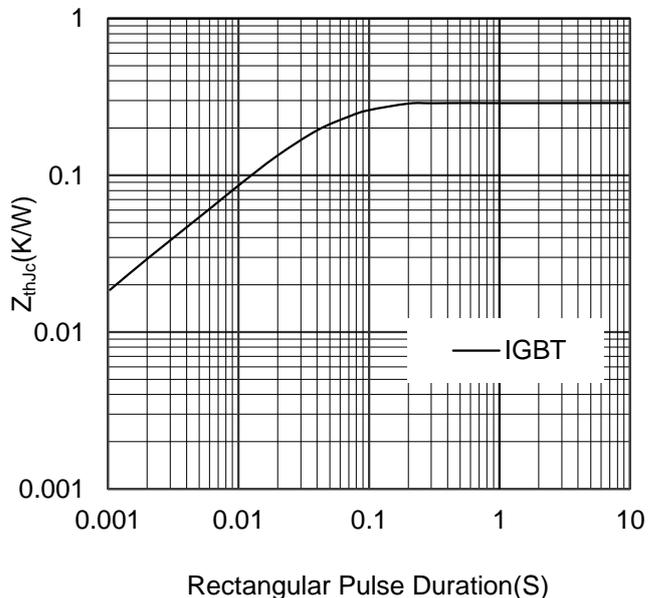
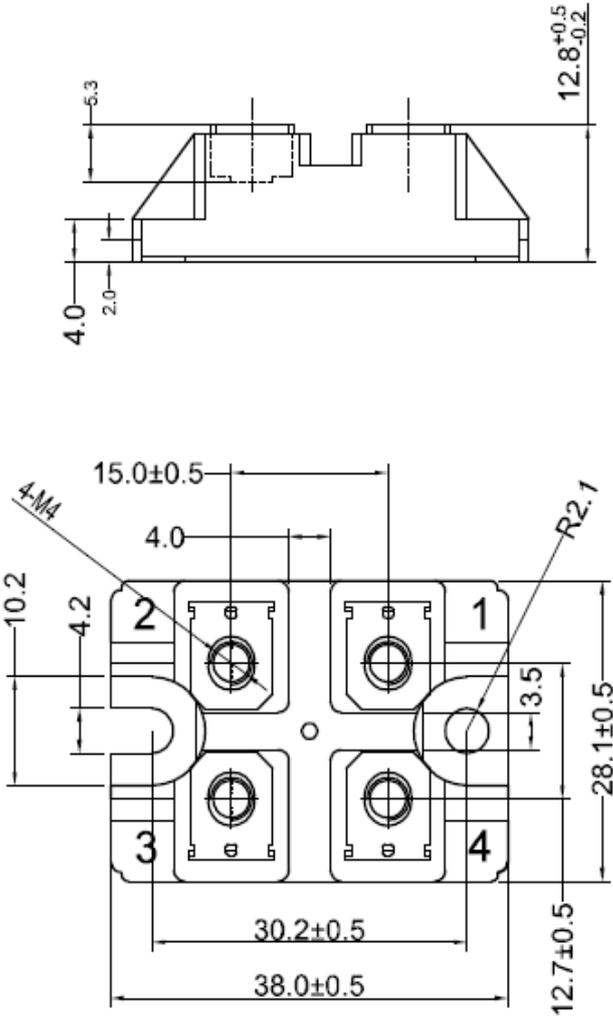


Figure 8. Transient Thermal Impedance of IGBT



Dimensions in (mm)
Figure 9. Package Outline